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Title of Invention:

PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE

First Named Inventor:

THOMAS GLENN

Domestic/Foreign Application:

Domestic Application

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9302

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TRANSMITTAL

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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE	
<p>Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P. Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids1-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND AND LEADFRAME FOR MAKING THE PACKAGE						
Application Number:	10/626150						
Confirmation Number:	9302						
First Named Applicant:	THOMAS GLENN						
Attorney Docket Number:	AMKOR007C2						
Art Unit:	2815						
Search string:	(2596993 or 3435815 or 3734660 or 3838984 or 4054238 or 4189342 or 4258381 or 4289922 or 4301464 or 4332537 or 4417266 or 4451224 or 4530152 or 4541003 or 4646710 or 4707724 or 4727633 or 4737839 or 4756080 or 4812896 or 4862245 or 4862246 or 4907067 or 4920074 or 4935803 or 4942454 or 4987475 or 5018003 or 5029386 or 5041902 or 5057900 or 5059379 or 5065223 or 5070039 or 5087961 or 5091341 or 5096852 or 5118298 or 5122860 or 5134773 or 5151039 or 5157475 or 5157480 or 5168368 or 5172213 or 5172214 or 5175060 or 5200362 or 5200809 or 5214845 or 20010008305 or 20010014538 or 20010011654 or 20020024122 20020027297 or 20020140061 or 20020140068 20020163015 or 20030030131 or 20030073265).pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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Signature

Examiner Name	Date